



## Atmel AT24C01C and AT24C02C

### I<sup>2</sup>C-Compatible (2-wire) Serial EEPROM

1-Kbit (128 x 8), 2-Kbit (256 x 8)

#### DATASHEET

#### Features

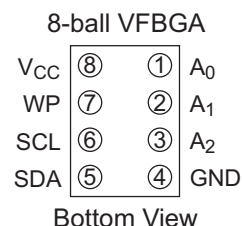
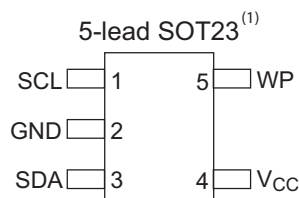
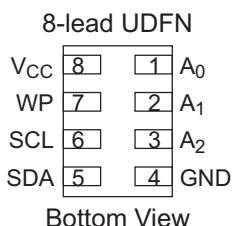
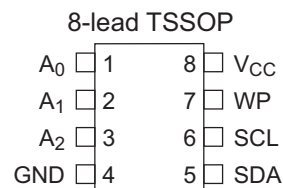
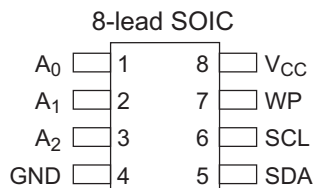
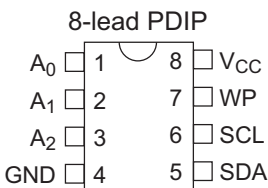
- Low-voltage operation
  - $V_{CC} = 1.7V$  to  $5.5V$
- Internally organized as 128 x 8 (1K) or 256 x 8 (2K)
- I<sup>2</sup>C compatible (2-wire) serial interface
- Schmitt Trigger, filtered inputs for noise suppression
- Bidirectional data transfer protocol
- 400kHz (1.7V) and 1MHz (2.5V, 2.7V, 5.0V) compatibility
- Write Protect pin for hardware data protection
- 8-byte Page Write mode
  - Partial page writes allowed
- Self-timed write cycle (5ms max)
- High-reliability
  - Endurance: 1,000,000 write cycles
  - Data retention: 100 years
- Green package options (Pb/Halide-free/RoHS-compliant)
  - 8-lead PDIP, 8-lead JEDEC SOIC, 8-lead TSSOP, 8-pad UDFN, 5-lead SOT23, and 8-ball VFBGA
- Die sale options: wafer form and tape and reel available

#### Description

The Atmel® AT24C01C/02C provides 1024/2048-bits of Serial Electrically Erasable and Programmable Read-Only Memory (EEPROM) organized as 128/256 words of eight bits each. Both devices include a cascading feature that allows up to eight devices to share a common 2-wire bus. These devices are optimized for use in many industrial and commercial applications where low power and low voltage operation are essential. The AT24C01C/02C are available in space saving 8-lead PDIP, 8-lead JEDEC SOIC, 8-lead TSSOP, 8-lead UDFN, 5-lead SOT23, and 8-ball VFBGA packages. In addition, the entire family operates from 1.7V to 5.5V  $V_{CC}$ .

## 1. Pin Configurations and Pinouts

Pin Name	Function
A <sub>0</sub> - A <sub>2</sub>	Address Inputs
SDA	Serial Data
SCL	Serial Clock Input
WP	Write Protect
GND	Ground
V <sub>CC</sub>	Power Supply



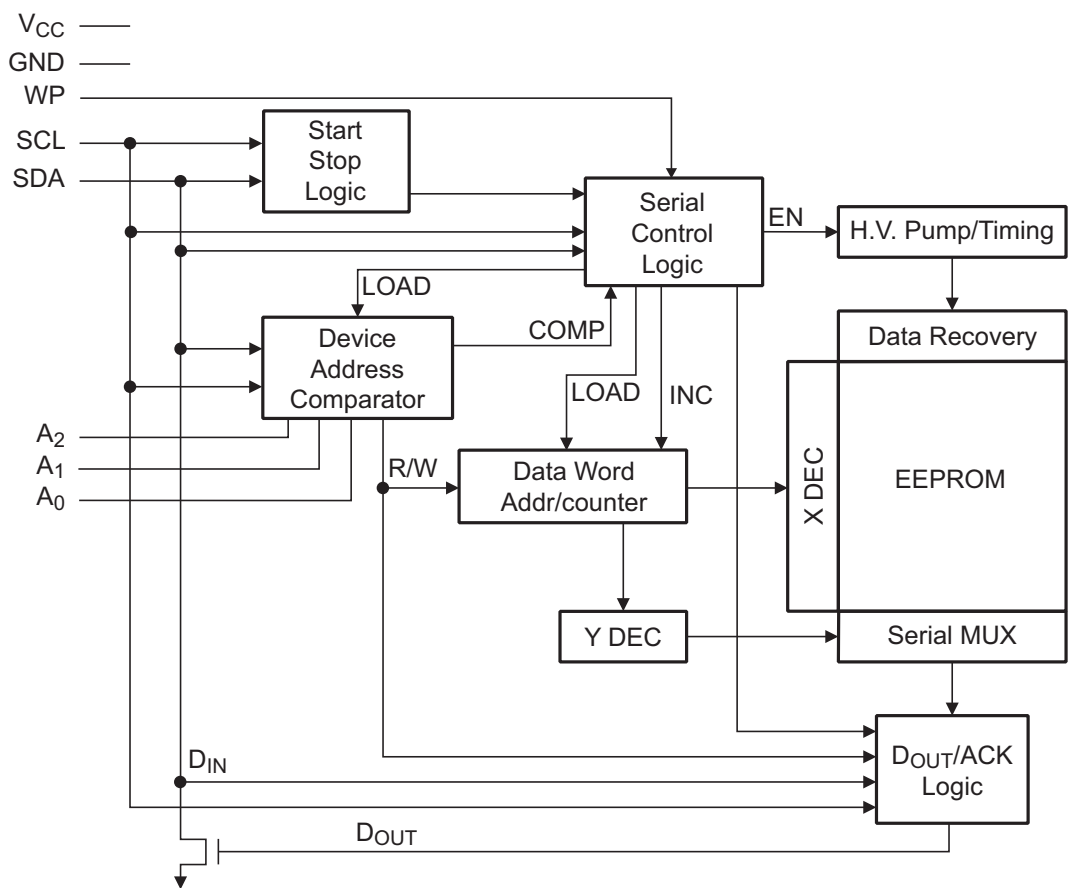
Note: 1. For use of 5-lead SOT23, the software A2, A1, and A0 bits in the device address word must be set to zero to properly communicate.

## 2. Absolute Maximum Ratings

Operating Temperature .....	-55°C to +125°C
Storage Temperature .....	-65°C to +150°C
Voltage on any pin with respect to ground .....	-1.0V to +7.0V
Maximum Operating Voltage .....	6.25V
DC Output Current.....	5.0mA

\*Notice: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### 3. Block Diagram



### 4. Pin Description

**Serial Clock (SCL):** The SCL input is used to positive edge clock data into each EEPROM device and negative edge clock data out of each device.

**Serial Data (SDA):** The SDA pin is bidirectional for serial data transfer. This pin is open drain driven and may be wire-ORed with any number of other open drain or open collector devices.

**Device/Page Addresses ( $A_2$ ,  $A_1$ ,  $A_0$ ):** The  $A_2$ ,  $A_1$ , and  $A_0$  pins are device address inputs that are hard wired for the AT24C01C/02C. As many as eight 1-Kbit or 2-Kbit devices may be addressed on a single bus system. See [Section 7. "Device Addressing" on page 9](#) for more details.

**Write Protect (WP):** The AT24C01C/02C have a Write Protect pin that provides hardware data protection. The Write Protect pin allows normal read/write operations when connected to ground (GND). When the Write Protect pin is connected to  $V_{CC}$ , the write protection feature is enabled and operates as shown below in [Table 4-1](#).

Table 4-1. Write Protect

WP Pin Status	Part of the Array Protected
	Atmel AT24C01C and AT24C02C
At $V_{CC}$	Full (2K) Array
At GND	Normal Read/Write Operations

## 5. Memory Organization

**Atmel AT24C01C, 1K Serial EEPROM:** Internally organized with 16 pages of eight bytes each, the 1K requires a 7-bit data word address for random word addressing.

**Atmel AT24C02C, 2K Serial EEPROM:** Internally organized with 32 pages of eight bytes each, the 2K requires an 8-bit data word address for random word addressing.

**Table 5-1. Pin Capacitance<sup>(1)</sup>**

Applicable over recommended operating range from  $T_A = 25^\circ\text{C}$ ,  $f = 1.0\text{MHz}$ ,  $V_{CC} = 1.7\text{V}$  to  $5.5\text{V}$

Symbol	Test Condition	Max	Units	Conditions
$C_{I/O}$	Input/Output Capacitance (SDA)	8	pF	$V_{I/O} = 0\text{V}$
$C_{IN}$	Input Capacitance ( $A_0$ , $A_1$ , $A_2$ , SCL)	6	pF	$V_{IN} = 0\text{V}$

Note: 1. This parameter is characterized and is not 100% tested.

**Table 5-2. DC Characteristics**

Applicable over recommended operating range from:  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 1.7\text{V}$  to  $5.5\text{V}$  (unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
$V_{CC1}$	Supply Voltage		1.7		5.5	V
$V_{CC2}$	Supply Voltage		2.5		5.5	V
$V_{CC3}$	Supply Voltage		4.5		5.5	V
$I_{CC1}$	Supply Current $V_{CC} = 5.0\text{V}$	Read at 400kHz		0.4	1.0	mA
$I_{CC2}$	Supply Current $V_{CC} = 5.0\text{V}$	Write at 400kHz		2.0	3.0	mA
$I_{SB1}$	Standby Current $V_{CC} = 1.7\text{V}$	$V_{IN} = V_{CC}$ or $V_{SS}$			1.0	$\mu\text{A}$
$I_{SB2}$	Standby Current $V_{CC} = 2.5\text{V}$	$V_{IN} = V_{CC}$ or $V_{SS}$			2.0	$\mu\text{A}$
$I_{SB3}$	Standby Current $V_{CC} = 5.5\text{V}$	$V_{IN} = V_{CC}$ or $V_{SS}$			6.0	$\mu\text{A}$
$I_{LI}$	Input Leakage Current	$V_{IN} = V_{CC}$ or $V_{SS}$		0.10	3.0	$\mu\text{A}$
$I_{LO}$	Output Leakage Current	$V_{OUT} = V_{CC}$ or $V_{SS}$		0.05	3.0	$\mu\text{A}$
$V_{IL}$	Input Low Level <sup>(1)</sup>		-0.6		$V_{CC} \times 0.3$	V
$V_{IH}$	Input High Level <sup>(1)</sup>		$V_{CC} \times 0.7$		$V_{CC} + 0.5$	V
$V_{OL1}$	Output Low Level $V_{CC} = 1.7\text{V}$	$I_{OL} = 0.15\text{mA}$			0.2	V
$V_{OL2}$	Output Low Level $V_{CC} = 3.0\text{V}$	$I_{OL} = 2.1\text{mA}$			0.4	V

Note: 1.  $V_{IL}$  min and  $V_{IH}$  max are reference only and are not tested.

**Table 5-3. AC Characteristics**

Applicable over recommended operating range from  $T_{AI} = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{CC} = 1.7\text{V}$  to  $5.5\text{V}$ ,  $CL = 1\text{TTL Gate and } 100\text{pF}$  (unless otherwise noted). Test conditions are listed in [Note 2](#).

Symbol	Parameter	1.7V		2.5V, 5.0V		Units
		Min	Max	Min	Max	
$f_{SCL}$	Clock Frequency, SCL		400		1000	kHz
$t_{LOW}$	Clock Pulse Width Low	1.2		0.4		$\mu\text{s}$
$t_{HIGH}$	Clock Pulse Width High	0.6		0.4		$\mu\text{s}$
$t_I$	Noise Suppression Time		100		50	ns
$t_{AA}$	Clock Low to Data Out Valid	0.1	0.9	0.05	0.55	$\mu\text{s}$
$t_{BUF}$	Time the bus must be free before a new transmission can start.	1.2		0.5		$\mu\text{s}$
$t_{HD,STA}$	Start Hold Time	0.6		0.25		$\mu\text{s}$
$t_{SU,STA}$	Start Setup Time	0.6		0.25		$\mu\text{s}$
$t_{HD,DAT}$	Data In Hold Time	0		0		$\mu\text{s}$
$t_{SU,DAT}$	Data In Setup Time	100		100		ns
$t_R$	Inputs Rise Time <sup>(1)</sup>		0.3		0.3	$\mu\text{s}$
$t_F$	Inputs Fall Time <sup>(1)</sup>		300		100	ns
$t_{SU,STO}$	Stop Setup Time	0.6		.25		$\mu\text{s}$
$t_{DH}$	Data Out Hold Time	50		50		ns
$t_{WR}$	Write Cycle Time		5		5	ms
Endurance <sup>(1)</sup>	3.3V, +25°C, Page Mode	1,000,000				Write Cycles

- Note:
1. This parameter is ensured by characterization only.
  2. AC measurement conditions:
    - $R_L$  (connects to  $V_{CC}$ ): 1.3 k $\Omega$  (2.5V, 5V), 10 k $\Omega$  (1.7V)
    - Input pulse voltages: 0.3  $V_{CC}$  to 0.7  $V_{CC}$
    - Input rise and fall times:  $\leq 50\text{ns}$
    - Input and output timing reference voltages: 0.5  $V_{CC}$

## 6. Device Operation

**Clock and Data Transitions:** The SDA pin is normally pulled high with an external device. Data on the SDA pin may change only during SCL low time periods (see [Figure 6-4 on page 8](#)). Data changes during SCL high periods will indicate a Start or Stop condition as defined below.

**Start Condition:** A high-to-low transition of SDA with SCL high is a Start condition which must precede any other command (see [Figure 6-5 on page 8](#)).

**Stop Condition:** A low-to-high transition of SDA with SCL high is a Stop condition. After a read sequence, the Stop command will place the EEPROM in a standby power mode (see [Figure 6-5 on page 8](#)).

**Acknowledge:** All addresses and data words are serially transmitted to and from the EEPROM in 8-bit words. The EEPROM sends a zero to acknowledge that it has received each word. This happens during the ninth clock cycle.

**Standby Mode:** The AT24C01C/02C features a low power standby mode which is enabled:

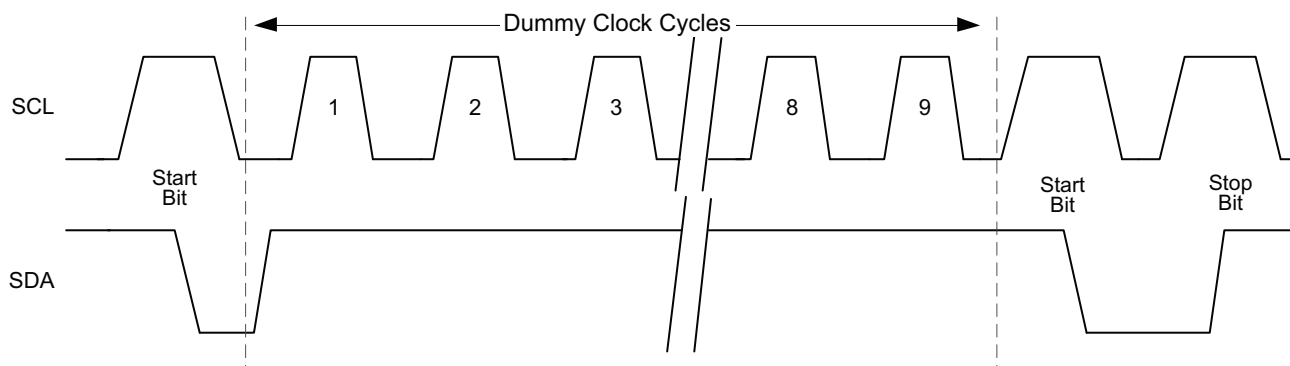
- Upon power-up.
- After the receipt of the stop bit and the completion of any internal operations.

**2-wire Software Reset:** After an interruption in protocol, power loss, or system reset, any 2-wire part can be reset by following these steps:

1. Create a start bit condition.
2. Clock nine cycles.
3. Create another start bit followed by stop bit condition as shown in [Figure 6-1](#).

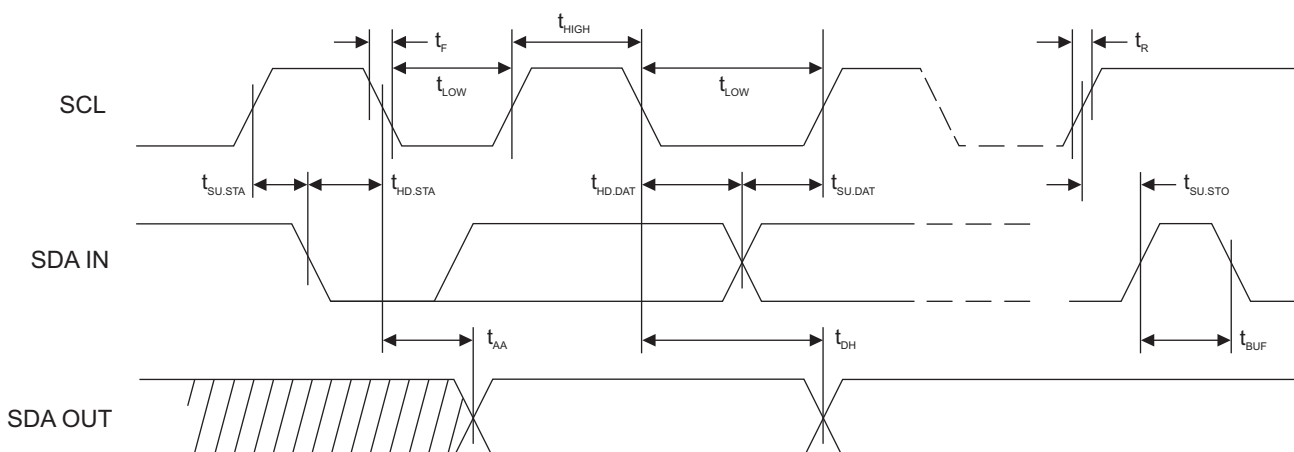
The device is ready for the next communication after above steps have been completed.

**Figure 6-1. Software reset**



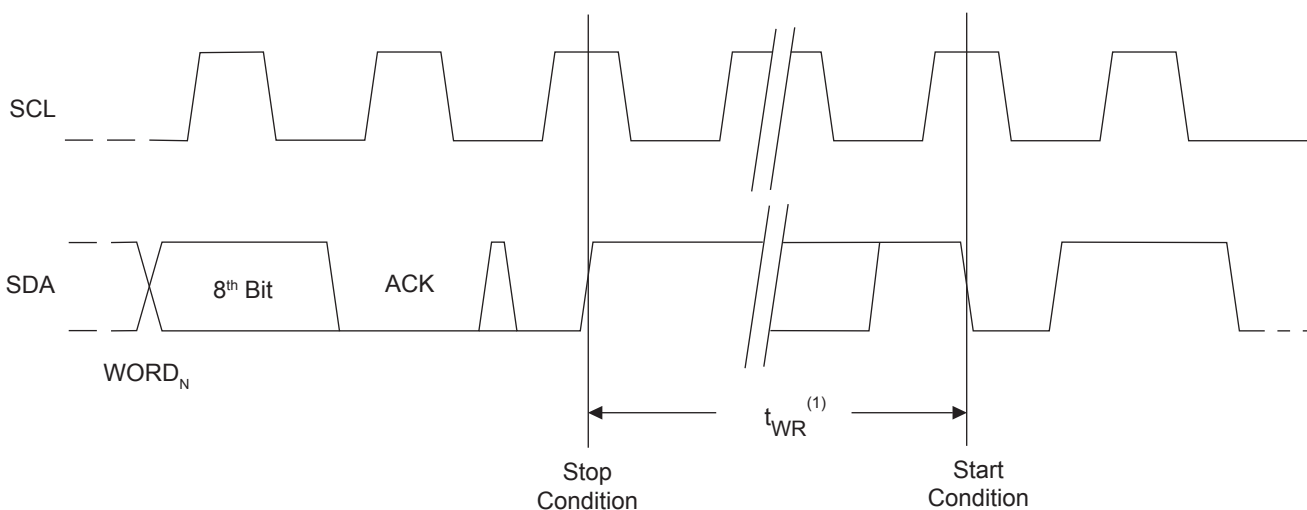
**Figure 6-2. Bus Timing**

SCL: Serial Clock, SDA: Serial Data I/O



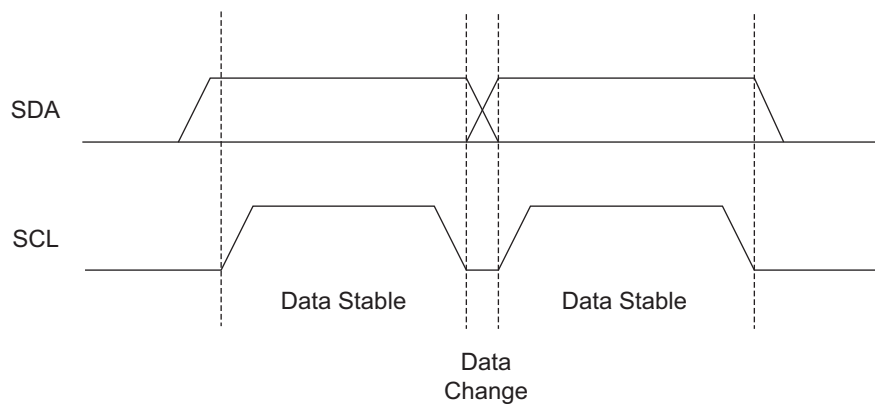
**Figure 6-3. Write Cycle Timing**

SCL: Serial Clock, SDA: Serial Data I/O

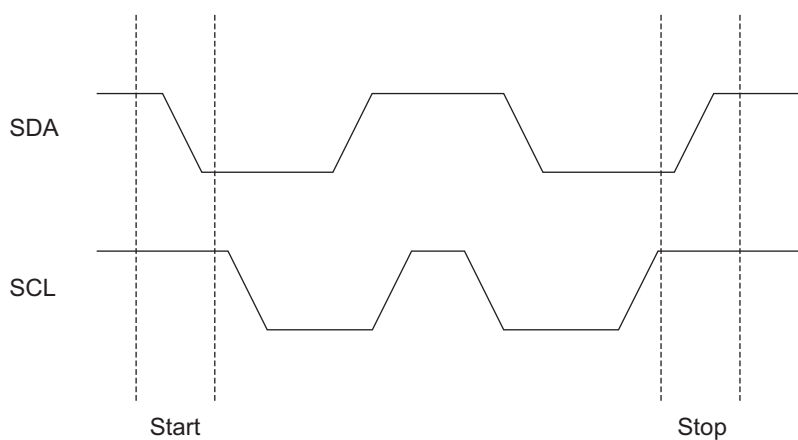


Notes: 1. The write cycle time  $t_{WR}$  is the time from a valid Stop condition of a write sequence to the end of the internal clear/write cycle.

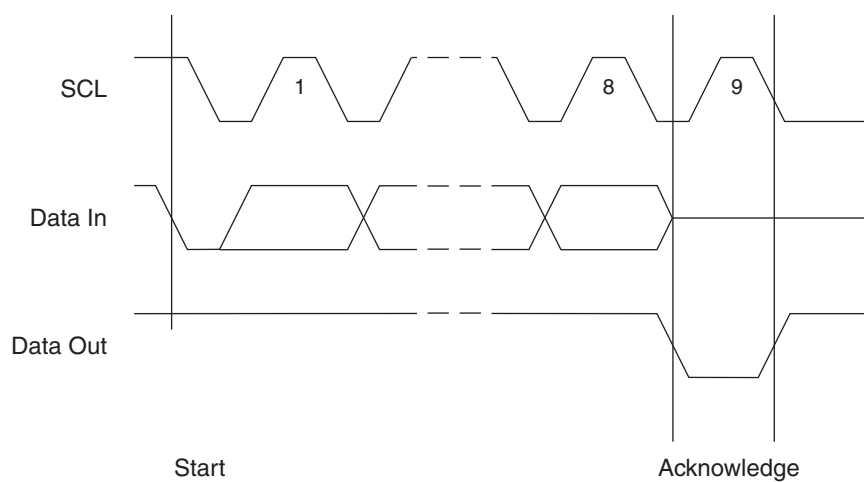
**Figure 6-4. Data Validity**



**Figure 6-5. Start and Stop Definition**



**Figure 6-6. Output Acknowledge**





## 7. Device Addressing

The 1-Kbit and 2-Kbit EEPROM device requires an 8-bit device address word following a start condition to enable the chip for a Read or Write operation.

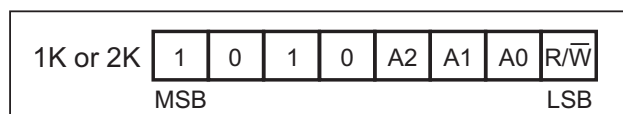
The device address word consists of a mandatory '1010' (0xA) sequence for the first four most significant bits as shown in [Figure 7-1](#). This is common to all Serial EEPROM devices.

The next three bits are the A<sub>2</sub>, A<sub>1</sub>, and A<sub>0</sub> device address bits for the 1K and 2K EEPROM. These three bits must compare to their corresponding hard-wired input pins A<sub>2</sub>, A<sub>1</sub>, and A<sub>0</sub> in order for the part to acknowledge.

The eighth bit of the device address is the Read/Write operation select bit. A Read operation is initiated if this bit is high and a Write operation is initiated if this bit is low.

Upon a valid compare of the device address with hard-wired input pins A<sub>2</sub>, A<sub>1</sub>, and A<sub>0</sub>, the EEPROM will output a zero. If a compare is not successfully made, the chip will return to a standby state.

**Figure 7-1. Device Address**



## 8. Write Operations

**Byte Write:** A Byte Write operation requires an 8-bit data word address following the device address word and acknowledgment. Upon receipt of this address, the EEPROM will again respond with a zero and then clock in the first 8-bit data word. Following receipt of the 8-bit data word, the EEPROM will output a zero and the addressing device, such as a microcontroller, must terminate the write sequence with a Stop condition. At this time, the EEPROM enters an internally timed write cycle,  $t_{WR}$ , to the nonvolatile memory. All inputs are disabled during this write cycle and the EEPROM will not respond until the write is complete (see [Figure 9-1 on page 10](#)).

**Page Write:** The 1-Kbit and 2-Kbit EEPROM are capable of an 8-byte Page Write.

A Page Write is initiated the same as a Byte Write, but the microcontroller does not send a Stop condition after the first data word is clocked in. Instead, after the EEPROM acknowledges receipt of the first data word, the microcontroller can transmit up to seven data words. The EEPROM will respond with a zero after each data word received. The microcontroller must terminate the page write sequence with a Stop condition (see [Figure 9-2 on page 10](#)).

The data word address lower three bits are internally incremented following the receipt of each data word. The higher data word address bits are not incremented, retaining the memory page row location. When the word address, internally generated, reaches the page boundary, the following byte is placed at the beginning of the same page. If more than eight data words are transmitted to the EEPROM, the data word address will “roll over” and previous data will be overwritten.

**Acknowledge Polling:** Once the internally timed write cycle has started and the EEPROM inputs are disabled, acknowledge polling can be initiated. This involves sending a Start condition followed by the device address word. The read/write bit is representative of the operation desired. Only if the internal write cycle has completed will the EEPROM respond with a zero allowing the read or write sequence to continue.

**Data Security:** The AT24C01C/02C has a hardware data protection scheme that allows the user to write protect the entire memory when the WP pin is at  $V_{CC}$ .

## 9. Read Operations

Read operations are initiated the same way as write operations with the exception that the read/write select bit in the device address word is set to one. There are three read operations:

- Current Address Read
- Random Address Read
- Sequential Read.

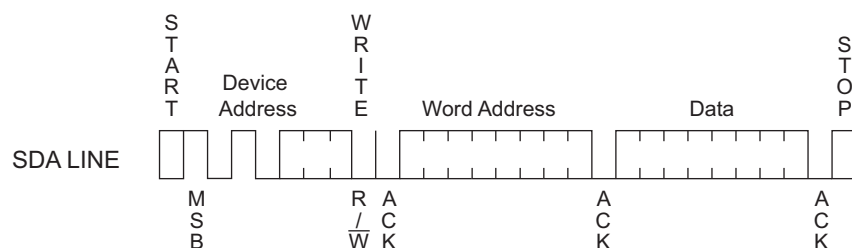
**Current Address Read:** The internal data word address counter maintains the last address accessed during the last read or write operation, incremented by one. This address stays valid between operations as long as the chip power is maintained. The address roll-over during read is from the last byte of the last memory page to the first byte of the first page. The address roll-over during write is from the last byte of the current page to the first byte of the same page.

Once the device address with the read/write select bit set to one is clocked in and acknowledged by the EEPROM, the current address data word is serially clocked out. The microcontroller does not respond with an zero but does generate a following Stop condition (see [Figure 9-3 on page 11](#)).

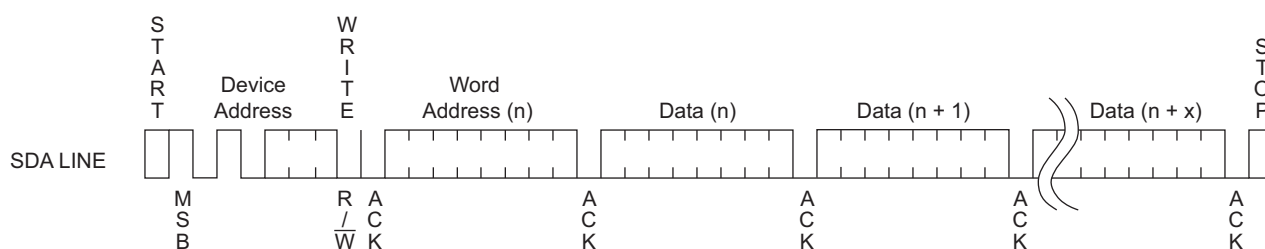
**Random Read:** A Random Read requires a dummy byte write sequence to load in the data word address. Once the device address word and data word address are clocked in and acknowledged by the EEPROM, the microcontroller must generate another start condition. The microcontroller now initiates a Current Address Read by sending a device address with the read/write select bit high. The EEPROM acknowledges the device address and serially clocks out the data word. The microcontroller does not respond with a zero but does generate a following stop condition (see [Figure 9-4 on page 11](#)).

**Sequential Read:** Sequential Reads are initiated by either a Current Address Read or a Random Address Read. After the microcontroller receives a data word, it responds with an acknowledge. As long as the EEPROM receives an acknowledge, it will continue to increment the data word address and serially clock out sequential data words. When the memory address limit is reached, the data word address will roll-over and the Sequential Read will continue. The Sequential Read operation is terminated when the microcontroller does not respond with a zero but does generate a following stop condition (see [Figure 9-5 on page 11](#)).

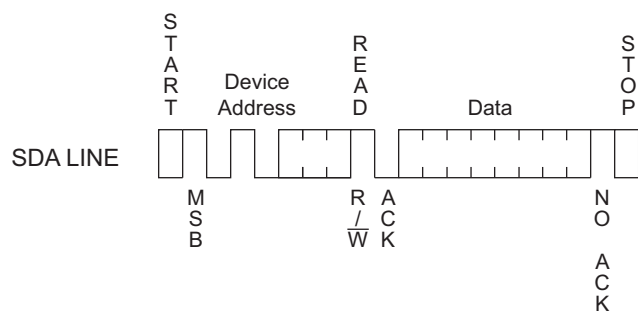
**Figure 9-1. Byte Write**



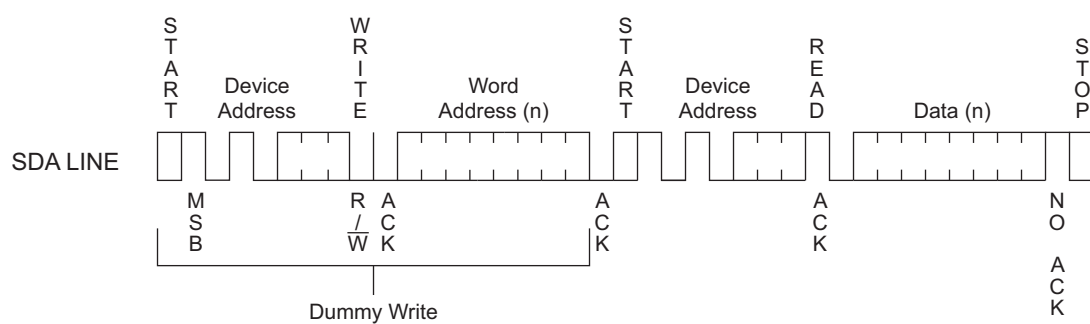
**Figure 9-2. Page Write**



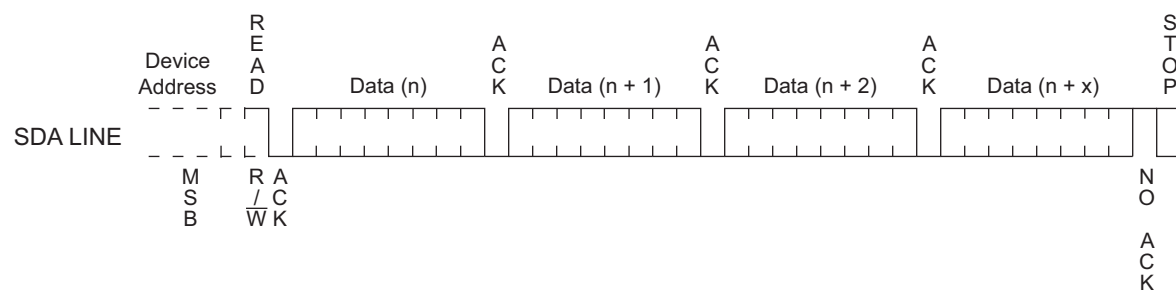
**Figure 9-3. Current Address Read**



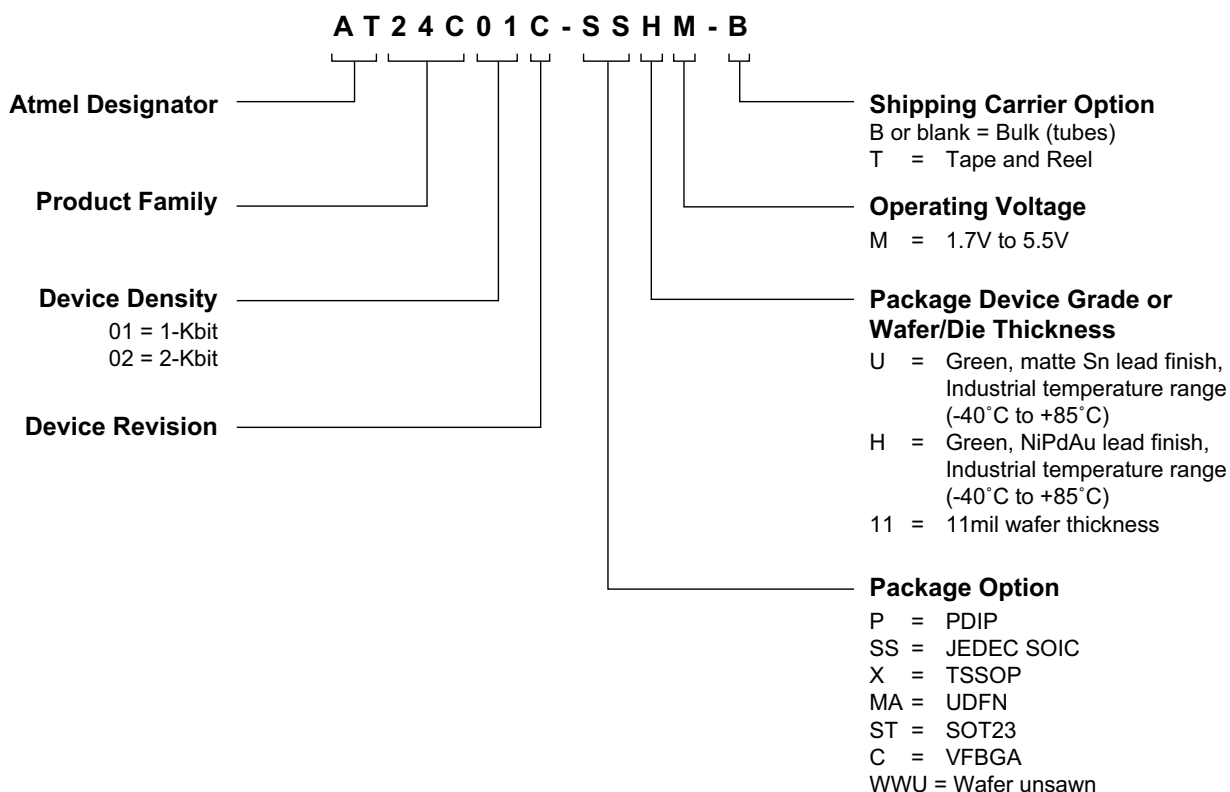
**Figure 9-4. Random Read**



**Figure 9-5. Sequential Read**



## 10. Ordering Code Detail



## 11. Part Markings

### AT24C01C and AT24C02C: Package Marking Information

8-lead PDIP	8-lead SOIC	8-lead TSSOP
8-lead UDFN	5-lead SOT-23	8-ball VFBGA
2.0 x 3.0 mm Body 		2.35 x 3.73 mm Body 

Note 1: ● designates pin 1

Note 2: Package drawings are not to scale

Catalog Number Truncation			
AT24C01C		Truncation Code ###: 01C	
AT24C02C		Truncation Code ###: 02C	
Date Codes			Voltages
Y = Year	M = Month	WW = Work Week of Assembly	M: 1.7V min
2: 2012	6: 2016	A: January	
3: 2013	7: 2017	B: February	
4: 2014	8: 2018	...	
5: 2015	9: 2019	L: December	
Country of Assembly		Lot Number	Grade/Lead Finish Material
@ = Country of Assembly		AAA...A = Atmel Wafer Lot Number	U: Industrial/Matte Tin H: Industrial/NiPdAu
Trace Code			Atmel Truncation
XX = Trace Code (Atmel Lot Numbers Correspond to Code) Example: AA, AB.... YZ, ZZ			AT: Atmel ATM: Atmel ATML: Atmel

5/4/12

 Package Mark Contact: DL-CSO-Assy_eng@atmel.com	TITLE	DRAWING NO.	REV.
	24C01-02CSM, AT24C01C and AT24C02C Package Marking Information	24C01-02CSM	A

## 12. Ordering Codes

### 12.1 Atmel AT24C01C Ordering Information

Ordering Code	Package	Voltage	Operation Range
AT24C01C-PUM (Bulk Form Only)	8P3	1.7V to 5.5V	Lead-free/Halogen-free/ Industrial Temperature (–40°C to 85°C)
AT24C01C-SSHM-B <sup>(1)</sup> (NiPdAu Lead Finish)	8S1		
AT24C01C-SSHM-T <sup>(2)</sup> (NiPdAu Lead Finish)	8S1		
AT24C01C-XHM-B <sup>(1)</sup> (NiPdAu Lead Finish)	8X		
AT24C01C-XHM-T <sup>(2)</sup> (NiPdAu Lead Finish)	8X		
AT24C01C-MAHM-T <sup>(2)</sup> (NiPdAu Lead Finish)	8MA2		
AT24C01C-STUM-T <sup>(2)</sup>	5TS1		
AT24C01C-CUM-T <sup>(2)</sup>	8U3-1		
AT24C01C-WWU11M <sup>(3)</sup>	Wafer Sale		Industrial Temperature (–40°C to 85°C)

- Notes:
1. B = Bulk (tubes)
  2. T = Tape and reel
    - SOIC = 4K per reel
    - TSSOP, UDFN, SOT23, and VFBGA = 5K per reel
  3. For Wafer sales, please contact Atmel Sales.

Package Type	
<b>8P3</b>	8-lead, 0.300" wide, Plastic Dual Inline (PDIP)
<b>8S1</b>	8-lead, 0.150" wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
<b>8X</b>	8-lead, 4.4mm body, Plastic Thin Shrink Small Outline (TSSOP)
<b>8MA2</b>	8-lead, 2.00mm x 3.00mm body, 0.50mm Pitch, Ultra Thin Dual Flat No Lead (UDFN)
<b>5TS1</b>	5-lead, 2.90mm x 1.60mm body, Plastic Thin Shrink Small Outline (SOT23)
<b>8U3-1</b>	8-ball, die Ball Grid Array (VFBGA)

## 12.2 Atmel AT24C02C Ordering Information

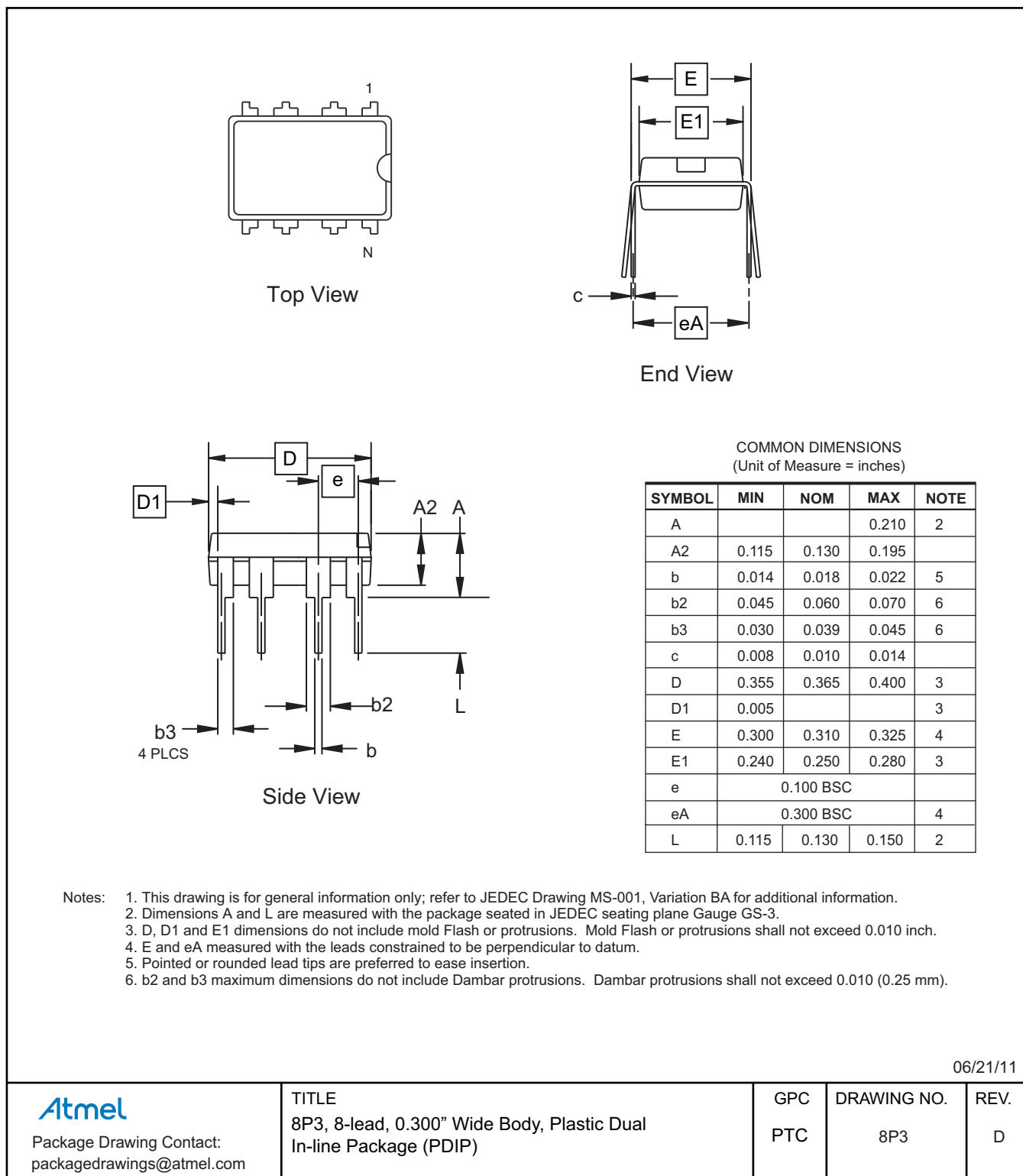
Ordering Code	Package	Voltage	Operation Range
AT24C02C-PUM (Bulk Form Only)	8P3	1.7V to 5.5V	Lead-free/Halogen-free/ Industrial Temperature (–40°C to 85°C)
AT24C02C-SSHM-B <sup>(1)</sup> (NiPdAu Lead Finish)	8S1		
AT24C02C-SSHM-T <sup>(2)</sup> (NiPdAu Lead Finish)	8S1		
AT24C02C-XHM-B <sup>(1)</sup> (NiPdAu Lead Finish)	8X		
AT24C02C-XHM-T <sup>(2)</sup> (NiPdAu Lead Finish)	8X		
AT24C02C-MAHM-T <sup>(2)</sup> (NiPdAu Lead Finish)	8MA2		
AT24C02C-STUM-T <sup>(2)</sup>	5TS1		
AT24C02C-CUM-T <sup>(2)</sup>	8U3-1		
AT24C02C-WWU11M <sup>(3)</sup>	Wafer Sale		Industrial Temperature (–40°C to 85°C)

- Notes:
1. B = Bulk (tubes)
  2. T = Tape and reel
    - SOIC = 4K per reel
    - TSSOP, UDFN, SOT23, and VFBGA = 5K per reel
  3. For Wafer sales, please contact Atmel Sales.

Package Type	
<b>8P3</b>	8-lead, 0.300" wide, Plastic Dual Inline (PDIP)
<b>8S1</b>	8-lead, 0.150" wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
<b>8X</b>	8-lead, 4.4mm body, Plastic Thin Shrink Small Outline (TSSOP)
<b>8MA2</b>	8-lead, 2.00mm x 3.00mm body, 0.50mm Pitch, Ultra Thin Dual Flat No Lead (UDFN)
<b>5TS1</b>	5-lead, 2.90mm x 1.60mm body, Plastic Thin Shrink Small Outline (SOT23)
<b>8U3-1</b>	8-ball, die Ball Grid Array (VFBGA)

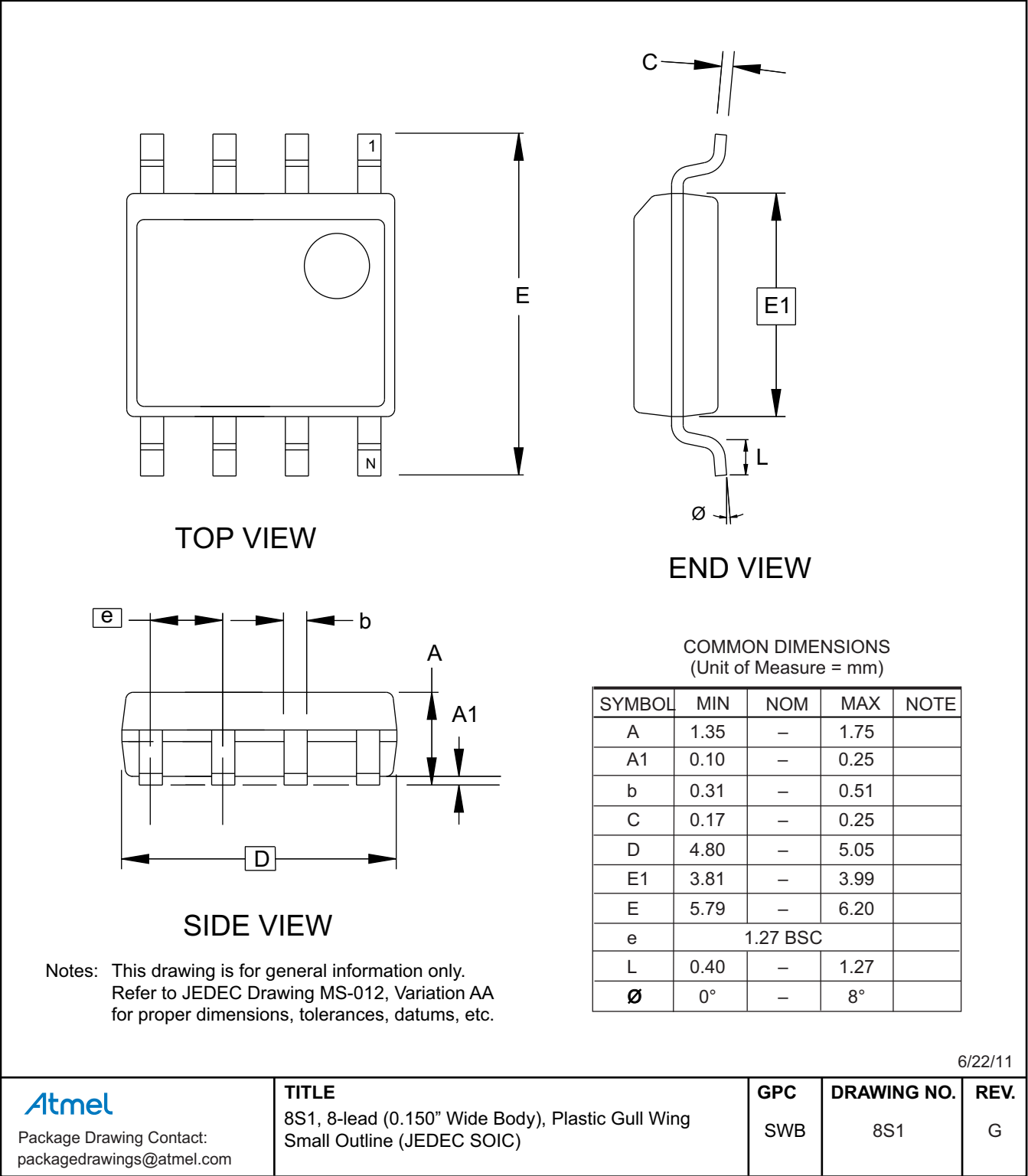
## 13. Packaging Information

### 13.1 8P3 — 8-lead PDIP

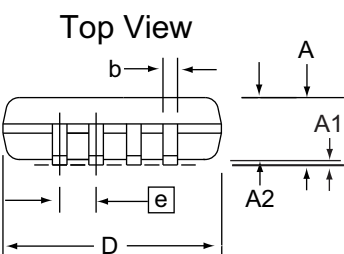
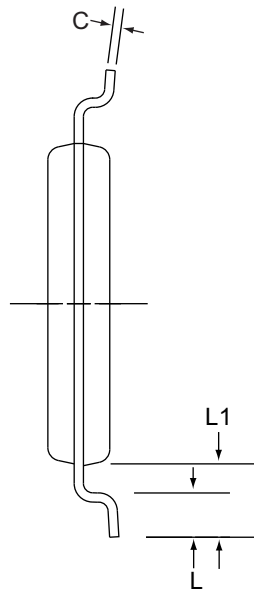
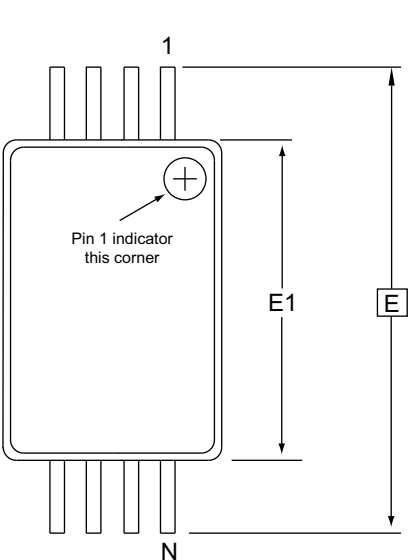




13.2 8S1 — 8-lead JEDEC SOIC



13.3 8X — 8-lead TSSOP



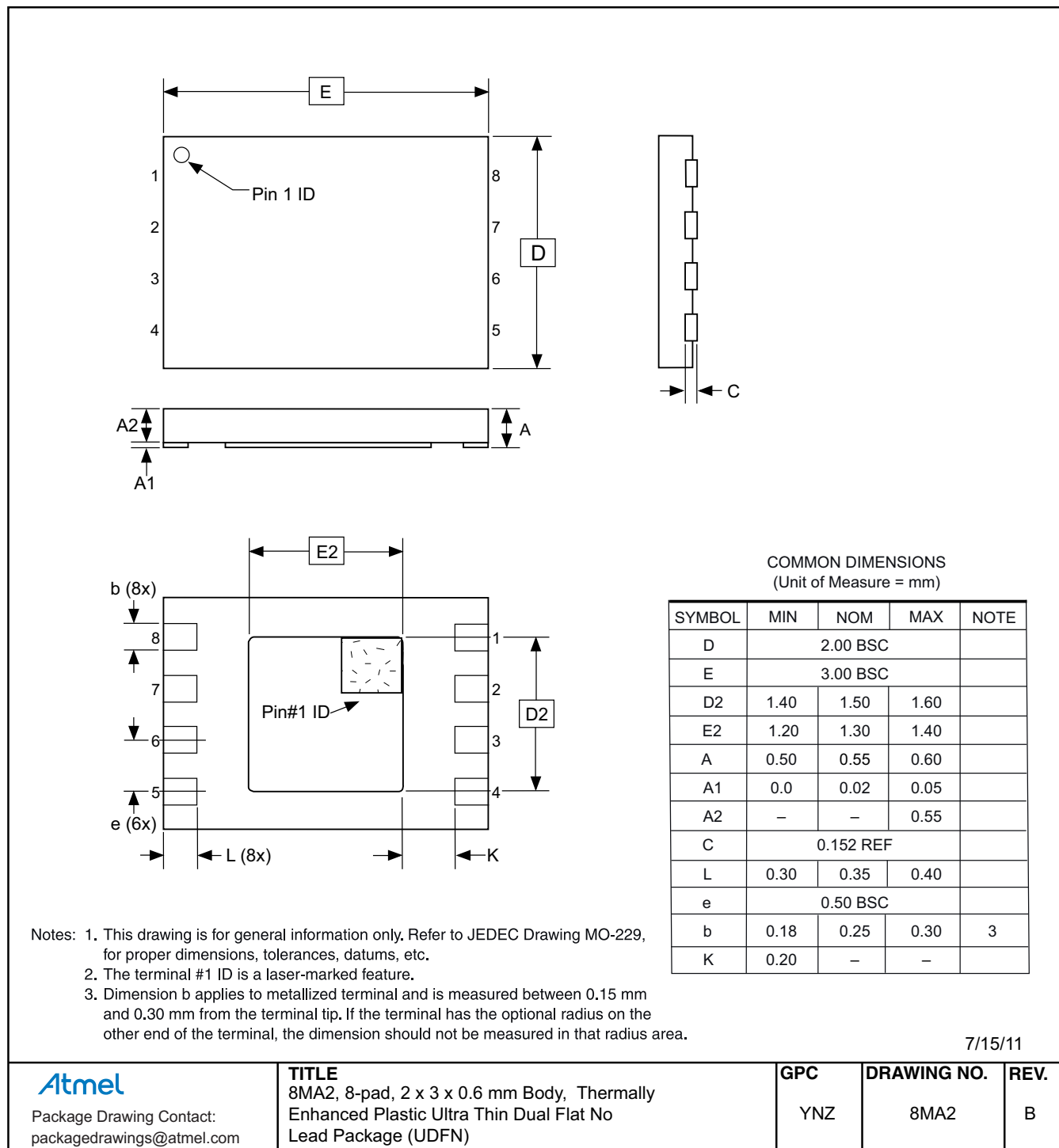
COMMON DIMENSIONS (Unit of Measure = mm)				
SYMBOL	MIN	NOM	MAX	NOTE
A	-	-	1.20	
A1	0.05	-	0.15	
A2	0.80	1.00	1.05	
D	2.90	3.00	3.10	2, 5
E	6.40 BSC			
E1	4.30	4.40	4.50	3, 5
b	0.19	-	0.30	4
e	0.65 BSC			
L	0.45	0.60	0.75	
L1	1.00 REF			
C		0.09	-	0.20

- Notes:
- 1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
  - 2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15mm (0.006in) per side.
  - 3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25mm (0.010in) per side.
  - 4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07mm.
  - 5. Dimension D and E1 to be determined at Datum Plane H.

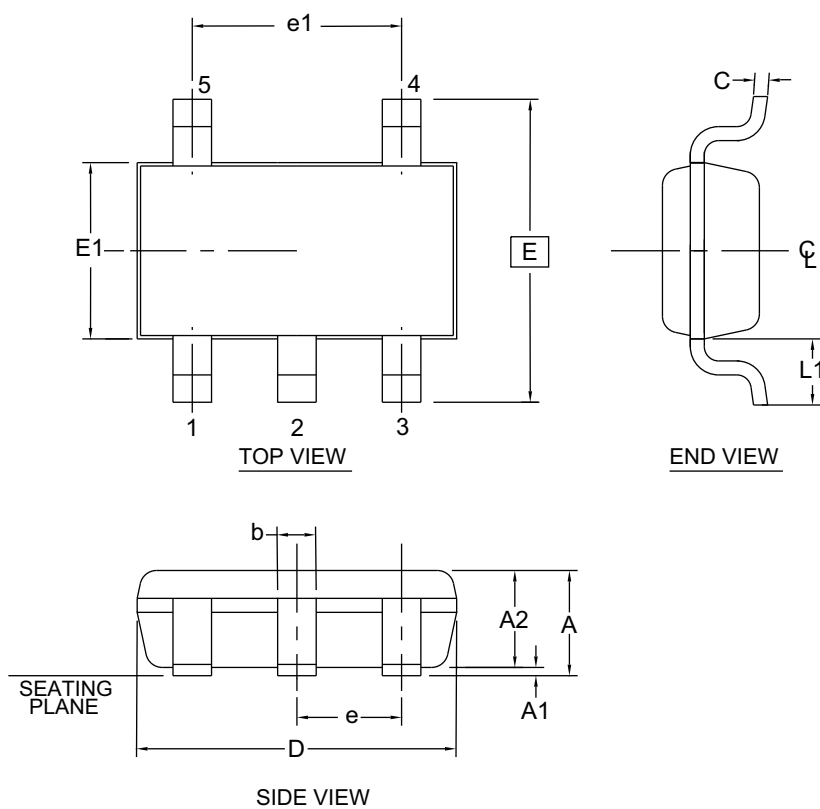
6/22/11

 Package Drawing Contact: packagedrawings@atmel.com	<b>TITLE</b> 8X, 8-lead 4.4mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)	<b>GPC</b>	<b>DRAWING NO.</b>	<b>REV.</b>
		TNR	8X	D

## 13.4 8MA2 — 8-pad UDFN



## 13.5 5TS1 — 5-lead SOT23



1. Dimension D does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.15 mm per side.
2. The package top may be smaller than the package bottom. Dimensions D and E1 are determined at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.
3. These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.
4. Dimension "b" does not include dambar protrusion. Allowable dambar protrusion shall be 0.08 mm total in excess of the "b" dimension at maximum material condition. The dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and an adjacent lead shall not be less than 0.07 mm.

This drawing is for general information only. Refer to JEDEC Drawing MO-193, Variation AB for additional information.

COMMON DIMENSIONS  
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-	-	1.00	
A1	0.00	-	0.10	
A2	0.70	0.90	1.00	
c	0.08	-	0.20	3
D	2.90 BSC			1,2
E	2.80 BSC			1,2
E1	1.60 BSC			1,2
L1	0.60 REF			
e	0.95 BSC			
e1	1.90 BSC			
b	0.30	-	0.50	3,4

5/31/12

**Atmel**

Package Drawing Contact:  
packagedrawings@atmel.com

TITLE

5TS1, 5-lead 1.60mm Body, Plastic Thin  
Shrink Small Outline Package (Shrink SOT)

GPC

TSZ

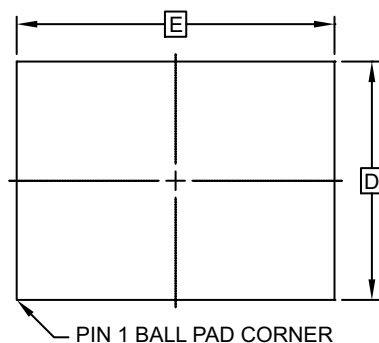
DRAWING NO.

5TS1

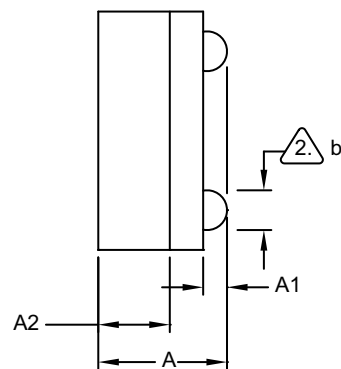
REV.

D

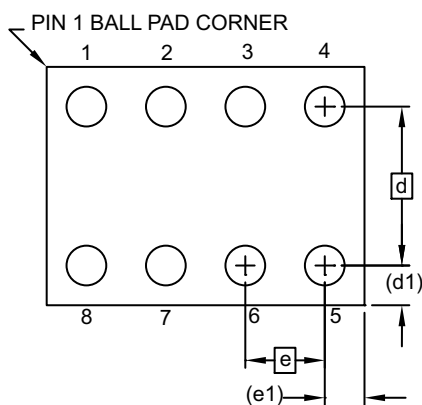
## 13.6 8U3-1 — 8-ball VFBGA



TOP VIEW



SIDE VIEW



BOTTOM VIEW  
8 SOLDER BALLS

Notes:

1. This drawing is for general information only.
2. Dimension 'b' is measured at maximum solder ball diameter.
3. Solder ball composition shall be 95.5Sn-4.0Ag-.5Cu.

COMMON DIMENSIONS  
(Unit of Measure - mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.73	0.79	0.85	
A1	0.09	0.14	0.19	
A2	0.40	0.45	0.50	
b	0.20	0.25	0.30	2
D	1.50 BSC			
E	2.0 BSC			
e	0.50 BSC			
e1	0.25 REF			
d	1.00 BSC			
d1	0.25 REF			

3/27/12

**Atmel**

Package Drawing Contact:  
packagedrawings@atmel.com

TITLE  
8U3-1, 8-ball, 1.50mm x 2.00mm body,  
0.50mm pitch, VFBGA Package

GPC  
GXU

DRAWING NO.  
8U3-1

REV.  
E

## 14. Revision History

Doc. Rev.	Date	Comments
8700F	06/2012	<p>Correct ordering codes:</p> <ul style="list-style-type: none"> <li>- AT24C01C-WWU11, Die Sale to AT24C01C-WWU11M, Wafer Sale.</li> <li>- AT24C02C-WWU11, Die Sale to AT24C02C-WWU11M, Wafer Sale.</li> </ul> <p>Remove WDT from ordering code detail.</p> <p>Update Atmel logos and disclaimer page.</p>
8700E	05/2012	<p>Update datasheet template.</p> <p>Add AT24C01C to document.</p> <p>Electrical performance improvements:</p> <ul style="list-style-type: none"> <li>- Reduce all ISB from legacy values</li> <li>- Increase 1MHz frequency range to include 2.5V operation.</li> </ul> <p>Update package drawings to latest versions (where applicable) and selected waveforms.</p>
8700D	08/2010	Change AT24C02C-XHM Part Marking from C02CM@ to 02CM @.
8700C	07/2010	<p>Ordering Information:</p> <ul style="list-style-type: none"> <li>- Change Atmel AT24C02C-TSUM-T to Atmel AT24C02C-STUM-T.</li> <li>- Change Atmel AT24C02CY6-MAHM-T to Atmel AT24C02C-MAHM-T.</li> <li>- Change Atmel AT24C02CU3-CUM-T to Atmel AT24C02C-CUM-T.</li> </ul> <p>Catalog numbering scheme, change TS = SOT23 to ST = SOT23.</p> <p>Part marking SOT23:</p> <ul style="list-style-type: none"> <li>- Change 2CMWU to 2CMBU.</li> <li>- Change W = Write Protection Feature to B = Write Protection.</li> </ul> <p>Part marking PDIP and SOIC: Added @ = Country of Assembly.</p> <p>Part marking TSSOP: Replaced and removed bottom mark.</p> <p>Part marking UDFN: Added HM@.</p> <p>Remove preliminary status.</p> <p>Change <math>t_{\text{I}}</math> Max 40 to 50 in Table AC Characteristics.</p>
8700B	02/2010	Correct catalog numbering scheme and ordering information.
8700A	12/2009	Initial document release.



Enabling Unlimited Possibilities®

**Atmel Corporation**

1600 Technology Drive  
San Jose, CA 95110  
USA

**Tel:** (+1) (408) 441-0311

**Fax:** (+1) (408) 487-2600

[www.atmel.com](http://www.atmel.com)

**Atmel Asia Limited**

Unit 01-5 & 16, 19F  
BEA Tower, Millennium City 5  
418 Kwun Tong Roa  
Kwun Tong, Kowloon  
HONG KONG

**Tel:** (+852) 2245-6100

**Fax:** (+852) 2722-1369

**Atmel Munich GmbH**

Business Campus  
Parking 4  
D-85748 Garching b. Munich  
GERMANY

**Tel:** (+49) 89-31970-0

**Fax:** (+49) 89-3194621

**Atmel Japan G.K.**

16F Shin-Osaki Kangyo Bldg  
1-6-4 Osaki, Shinagawa-ku  
Tokyo 141-0032  
JAPAN

**Tel:** (+81) (3) 6417-0300

**Fax:** (+81) (3) 6417-0370

© 2012 Atmel Corporation. All rights reserved. / Rev.: 8700F-SEEPR-6/12

Atmel®, Atmel logo and combinations thereof, Enabling Unlimited Possibilities®, and others are registered trademarks or trademarks of Atmel Corporation or its subsidiaries. Other terms and product names may be trademarks of others.

Disclaimer: The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. EXCEPT AS SET FORTH IN THE ATMEL TERMS AND CONDITIONS OF SALES LOCATED ON THE ATMEL WEBSITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNITIVE, SPECIAL OR INCIDENTAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS AND PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and products descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically provided otherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel products are not intended, authorized, or warranted for use as components in applications intended to support or sustain life.